

In the Specification

Please replace paragraph [0010] with the following amended paragraph:

[0010] Accordingly, the barrel pin is ~~tin-plated~~ nickel-plated so that a wetting ability thereof becomes relatively worse.

Please replace paragraph [0025] with the following amended paragraph:

[0025] Because the barrel pin 201 is ~~tin-plated~~ nickel-plated in advance, a wetting ability thereof is poor and the whole barrel pin will not be filled with solder owing to the capillarity during passing through the air reflow oven. Therefore, the space for holding the wiring can stay clear. At this time, because the riveted and soldered end of the barrel pin 201 on the printed circuit board is completed sealed, the wiring 203 will not be penetrated through the barrel pin 201 and also the printed circuit board 200 when sequentially being inserted into the barrel pin 201. Moreover, after the barrel pin 201 is riveted and soldered on the printed circuit board and the wiring 203 is fixed and fastened inside the barrel pin 201, the solder on the printed circuit board 200 will not be rent because of a pulling or twisting force applying on the wiring 203.